

AMENDMENTS TO THE SPECIFICATION

Page 25, line 16 to page 26, line 2:

The above-described electrically conductive paste is filled in the through holes and, thereby, unfired via hole conductors 15 are formed. Furthermore, the electrically conductive paste is applied to the substrate ceramic green sheets or the constraint layers 13 by a screen printing method, a transfer method, or the like and, thereby, unfired conductor films 14 are formed. The electrically conductive paste according to the present invention can be used for either of the conductor film 14 and the via hole conductor 15. However, ~~the~~ use for the via hole conductor 15, to which the constraint force of the constraint layer ~~44~~ 13 is difficult to extend, is particularly preferable.